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(54) **ELECTRICAL CONNECTION STRUCTURE AND ELECTRONIC DEVICE COMPRISING THE SAME**  
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(57) **ABSTRACT**  
An electrical connection structure is provided. The electrical connection structure includes a plurality of conductive particles and a connection pad including a first part, a second part and a third part. The first part is formed on an array substrate and electrically connected to a circuit of the array substrate. The second part is connected to the first part and passes through the array substrate. The third part is connected to the second part and electrically connected to a circuit of a circuit substrate through the conductive particles.

